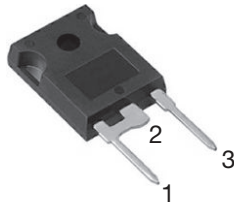
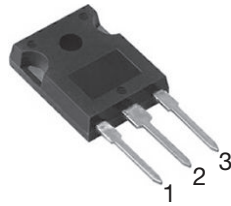
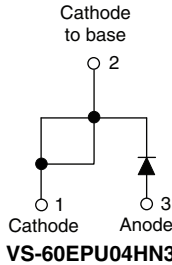
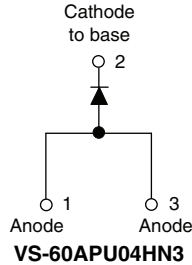


## Ultrafast Soft Recovery Diode, 60 A FRED Pt<sup>®</sup>


**TO-247AC modified**

**TO-247AC**


### FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- AEC-Q101 qualified, meets JESD 201 class 1A whisker test
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

### BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

### DESCRIPTION / APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

### MECHANICAL DATA

**Case:** TO-247AC modified (2 pins), TO-247AC  
Molding compound meets UL 94 V-0 flammability rating  
**Terminals:** matte tin plated leads, solderable per J-STD-002

### LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	60 A
$V_R$	400 V
$V_F$ at $I_F$	0.87 V
$t_{rr}$ typ.	50 ns
$T_J$ max.	175 °C
Package	TO-247AC modified (2 pins), TO-247AC
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_R$		400	V
Continuous forward current	$I_{F(AV)}$	$T_C = 127\text{ °C}$	60	A
Single pulse forward current	$I_{FSM}$	$T_C = 25\text{ °C}$	600	
Maximum repetitive forward current	$I_{FRM}$	Square wave, 20 kHz	120	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\ \mu\text{A}$	400	-	-	V
Forward voltage	$V_F$	$I_F = 60\text{ A}$	-	1.05	1.25	
		$I_F = 60\text{ A}, T_J = 175\text{ °C}$	-	0.87	1.03	
		$I_F = 60\text{ A}, T_J = 125\text{ °C}$	-	0.93	1.10	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	-	50	$\mu\text{A}$
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	2	$\text{mA}$
Junction capacitance	$C_T$	$V_R = 400\text{ V}$	-	50	-	$\text{pF}$
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	3.5	-	$\text{nH}$



DYNAMIC RECOVERY CHARACTERISTICS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1\text{ A}$ , $di_F/dt = 200\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	50	-	ns
		$T_J = 25\text{ }^\circ\text{C}$	-	85	-	
		$T_J = 125\text{ }^\circ\text{C}$	-	145	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^\circ\text{C}$	-	8.8	-	A
		$T_J = 125\text{ }^\circ\text{C}$	-	15.4	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^\circ\text{C}$	-	375	-	nC
		$T_J = 125\text{ }^\circ\text{C}$	-	1120	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction to case	$R_{thJC}$		-	-	0.70	K/W
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth, and greased	-	0.2	-	
Weight			-	5.5	-	g
			-	0.2	-	oz.
Mounting torque			1.2 (10)	-	2.4 (20)	N · m (lb · in)
Marking device		Case style TO-247AC modified	60EPU04H			
		Case style TO-247AC	60APU04H			

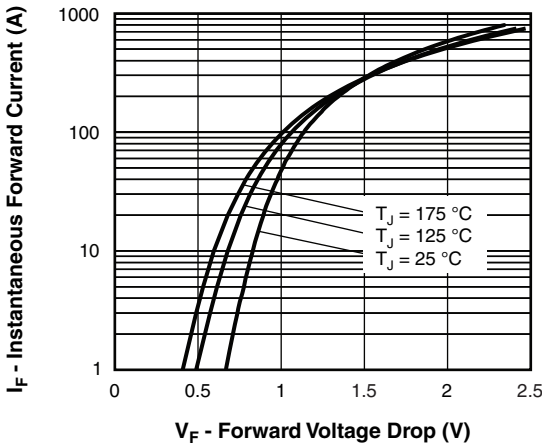


Fig. 1 - Typical Forward Voltage Drop Characteristics

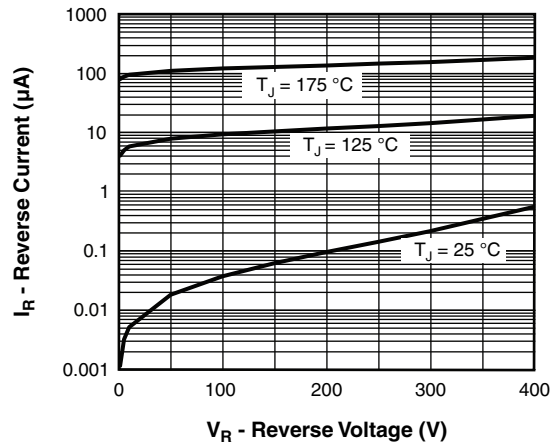


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

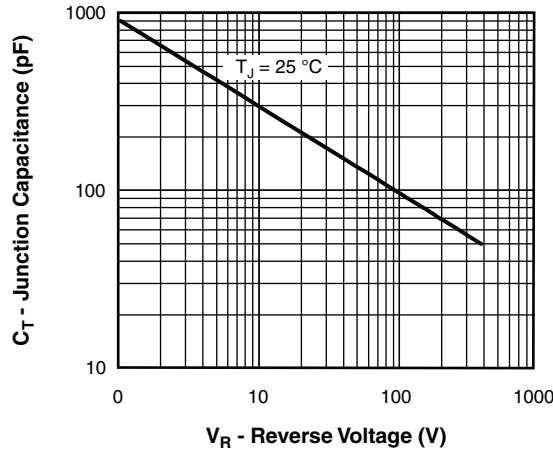


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

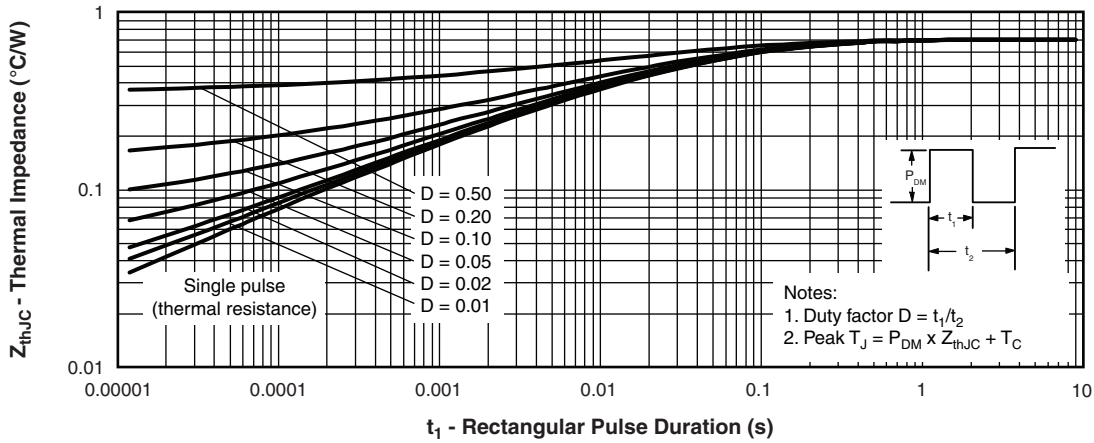


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

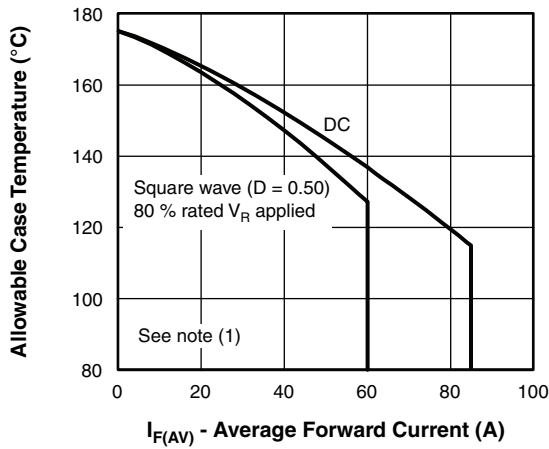


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

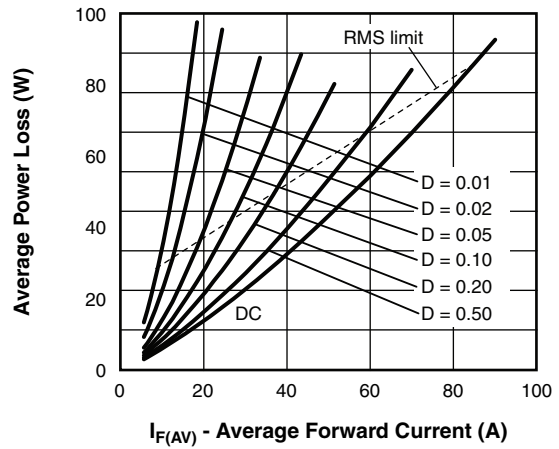


Fig. 6 - Forward Power Loss Characteristics

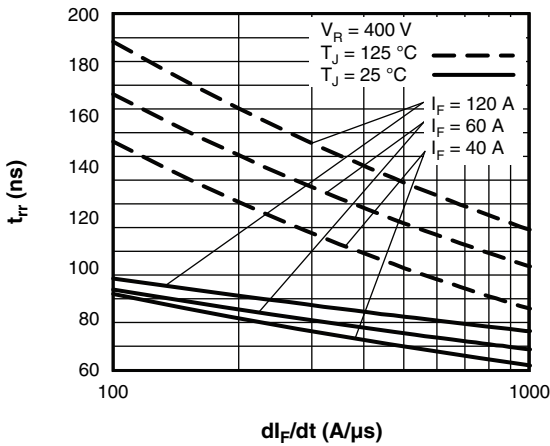


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$

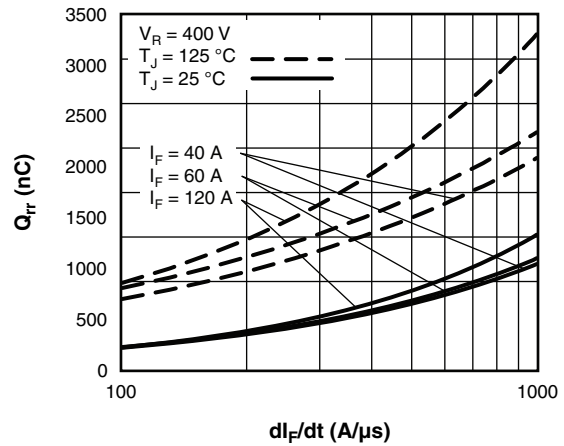


Fig. 8 - Typical Stored Charge vs.  $di_F/dt$

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$ ;
- $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);
- $P_{d_{REV}}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = 80\%$  rated  $V_R$

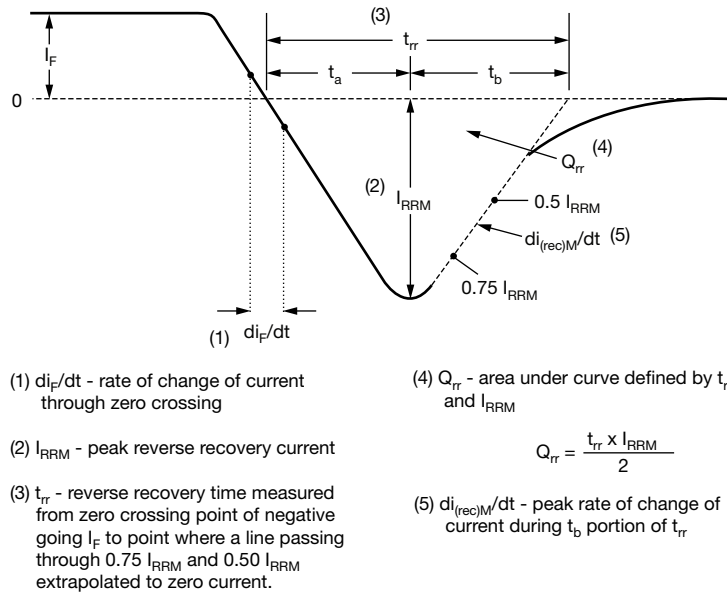
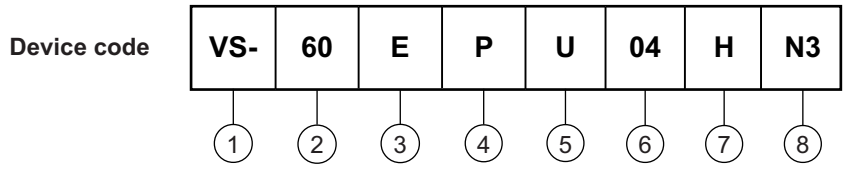


Fig. 9 - Reverse Recovery Waveform and Definitions



## ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (60 = 60 A)
- 3** - Circuit configuration:
  - E = single diode
  - A = single diode, 3 pins
- 4** - Package:
  - P = TO-247AC (modified)
- 5** - Type of silicon:
  - U = ultrafast recovery
- 6** - Voltage rating (04 = 400 V)
- 7** - H = AEC-Q101 qualified
- 8** - Environmental digit:
  - N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

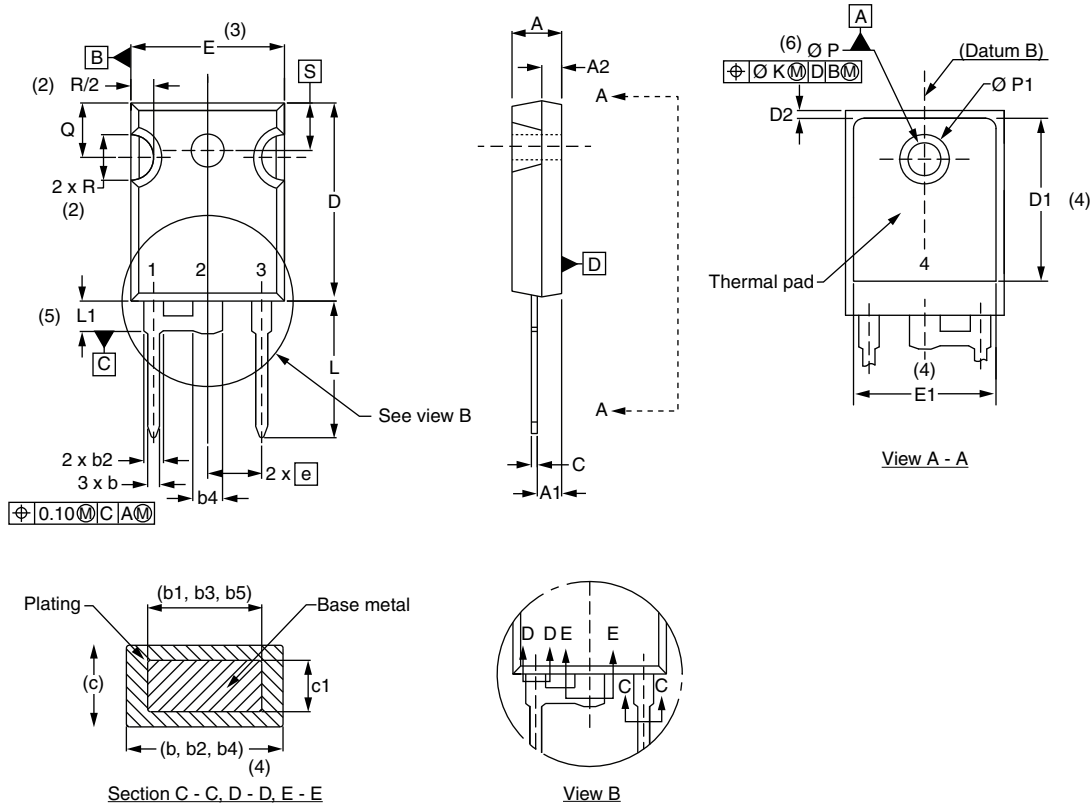
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-60EPU04HN3	25	500	Antistatic plastic tube
VS-60APU04HN3	25	500	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions	TO-247AC modified	<a href="http://www.vishay.com/doc?95541">www.vishay.com/doc?95541</a>
	TO-247AC	<a href="http://www.vishay.com/doc?95542">www.vishay.com/doc?95542</a>
Part marking information	TO-247AC modified-N3	<a href="http://www.vishay.com/doc?95442">www.vishay.com/doc?95442</a>
	TO-247AC-N3	<a href="http://www.vishay.com/doc?95007">www.vishay.com/doc?95007</a>
SPICE model		<a href="http://www.vishay.com/doc?96899">www.vishay.com/doc?96899</a>



TO-247AC modified - 50 mils L/F

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209		D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102		E	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054		E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055		e	5.46 BSC		0.215 BSC		
b1	0.99	1.35	0.039	0.053		$\Phi$ K	0.254		0.010		
b2	1.65	2.39	0.065	0.094		L	14.20	16.10	0.559	0.634	
b3	1.65	2.34	0.065	0.092		L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135		$\Phi$ P	3.56	3.66	0.14	0.144	
b5	2.59	3.38	0.102	0.133		$\Phi$ P1	-	7.39	-	0.291	
c	0.38	0.89	0.015	0.035		Q	5.31	5.69	0.209	0.224	
c1	0.38	0.84	0.015	0.033		R	4.52	5.49	0.178	0.216	
D	19.71	20.70	0.776	0.815	3	S	5.51 BSC		0.217 BSC		
D1	13.08	-	0.515	-	4						

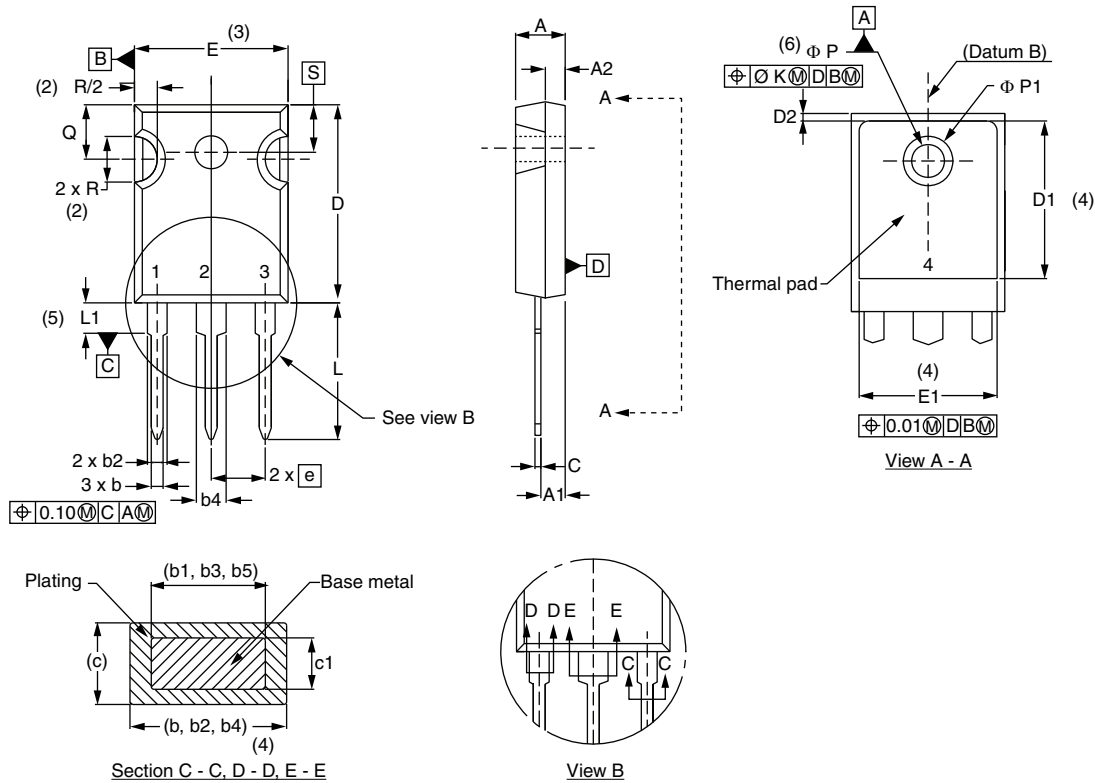
**Notes**

- (1) Dimensioning and tolerance per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6)  $\Phi$  P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q



TO-247AC - 50 mils L/F

DIMENSIONS in millimeters and inches



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b	0.99	1.40	0.039	0.055		e	5.46 BSC		0.215 BSC		
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